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January 13, 2004

To: Commissioner for Patents
P.O.Box 1450

Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572 28 Davis Avenue Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/697,746 10/30/03

Tze Ho Chan et al.

METHOD TO SELECTIVELY FORM POLY SiGe P TYPE ELECTRODE AND POLY-SILICON N TYPE ELECTRODE THROUGH PLANARIZATION

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation

In An Application.

The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

CS-01-193

The following three U.S. Patents disclose dual gate oxide processes:

- 1) U.S. Patent 6,358,819 to Shelton et al., "Dual Gate Oxide Process for Deep Submicron ICs."
- 2) U.S. Patent 5,918,116 to Chittipeddi, "Process for Forming Gate Oxides Possessing Different Thicknesses on a Semiconductor Substrate."
- 3) U.S. Patent 6,063,670 to Lin et al., "Gate Fabrication Processes for Split-Gate Transistors."
- U.S. Patent 6,342,438 to Yu et al., "Method of Manufacturing a Dual Doped CMOS Gate," teaches doping PMOS and NMOS regions differently before patterning polysilicon gates.
- U.S. Patent 5,356,821 to Naruse et al., "Method for Manufacturing Semiconductor Integrated Circuit Device," discloses epitaxial growth of SiGe gates for both NMOS and PMOS.
- U.S. Patent 6,376,323 to Kim et al., "Fabrication of Gate of P-Channel Field Effect Transistor with Added Implantation Before Pattering of the Gate," teaches PolySiGe gates for both PMOS and NMOS with selective doping.

CS-01-193

CS-01-093 serial number 10/266,425, filed 10/08/02, to Chew-Hoe Ang et al., "Dual Si-Ge Polysilicon Gate with Different Ge Concentrations for CMOS Device Optimization," discloses a method for forming SiGe gates having different Ge concentrations for PMOS and NMOS.

Sincerely

Stephen B. Ackerman,

Reg. No. 37761

citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.